

## **Welco<sup>TM</sup> LED120**T7 SAC305 No-Clean Printing Paste

Welco<sup>TM</sup> LED120 T7 SAC305 is a state-of-the-art no-clean printing paste, engineered primarily for miniLED and microLED attach applications. Paste release performance is exceptional at 70um stencil openings and highly consistent over its stencil life. LED120 series uses only Heraeus proprietary Welco<sup>TM</sup> Type 7 powders to achieve highly reliable solder joints with low voids for customers' applications.

## **Key Features**

- Uses high-quality Welco<sup>™</sup> T7 SAC305 powders
- Halogen-free and No-clean chemistry
- Best-in-class low-void performance
- Minimal solder beading
- Consistent fine pitch paste release
- Long stencil life (≥10hr) & staging life (≥10hr)
- Proven reliability and shear strength in miniLED application

## **End Applications**

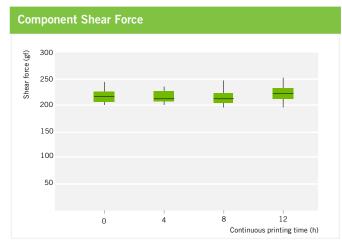
- Mini and microLED backlight (TV, tablets, videowall, etc)
- System-in-package (mobile, wearables, etc)



## Application Process Printing Die Attach Reflow Solvent Clean (optional)

Suitable for both mini and microLED die attach, and SiP flip chip and component attach processes

Continuous Printing	O hr	4 hr	8 hr	12 hr
Low void performance (<10%) 008004 component post reflow x-ray inspection	0-0 0-0	0-0 0-0	0-0 0-0	0-0 0-0
Consistent fine pitch paste release 70um Stencil Opening 50um line spacing				



Product Properties	LED120 T7 Paste	
Alloy	Sn/Ag3/Cu0.5	
Melting Point	217 - 219 °C	
Powder Type	Welco <sup>™</sup> Type 7	
Particle Size	2 - 11 μm	
Halogen Content	Halogen free	
Flux Classification	No-Clean / Solvent Clean	
Applications	Printing	

- Consistent high shear force achieved on 008004 components
- $\blacksquare$  Pad finishing is ENIG; and pad size is 130 x 140  $\mu m$

Americas

Phone +1 610 825 6050 electronics.americas@heraeus.com

Asia Pacific

Phone +65 6571 7649 electronics.apac@heraeus.com

China

Phone +86 53 5815 9601 electronics.china@heraeus.com

Europe, Middle East and Africa

Phone +49 6181 35 4370 electronics.emea@heraeus.com

The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contrally) and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application. The Heraeus logo, Heraeus, Welco<sup>®</sup> and the Welco figurative mark are trademarks or registered trademarks of Heraeus Holding GmbH or its affiliates. All rights reserved.